imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DMC204C0

Silicon NPN epitaxial planar type

For low frequency amplification

Features

- \bullet High forward current transfer ratio h_{FE} with excellent linearity
- \bullet Low collector-emitter saturation voltage $V_{CE(sat)}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: D5

Basic Part Number

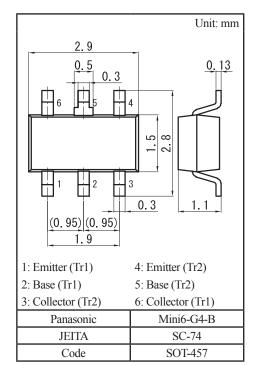
Dual DSC2C01 (Individual)

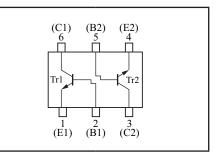
Packaging

DMC204C00R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Absolute Maximum Ratings $T_a = 25^{\circ}C$

	Parameter	Symbol Rating		Unit	
Tr1 Tr2	Collector-base voltage (Emitter open)	V _{CBO}	V _{CBO} 100		
	Collector-emitter voltage (Base open)	V _{CEO}	100	V	
	Emitter-base voltage (Collector open)	V _{EBO} 15		V	
	Collector current	I _C 20		mA	
	Peak collector current	I _{CP}	50	mA	
Overall	Total power dissipation	P _T	300	mW	
	Junction temperature	Tj	150	°C	
	Operating ambient temperature	T _{opr} -40 to +85		°C	
	Storage temperature	T _{stg}	-55 to +150	°C	



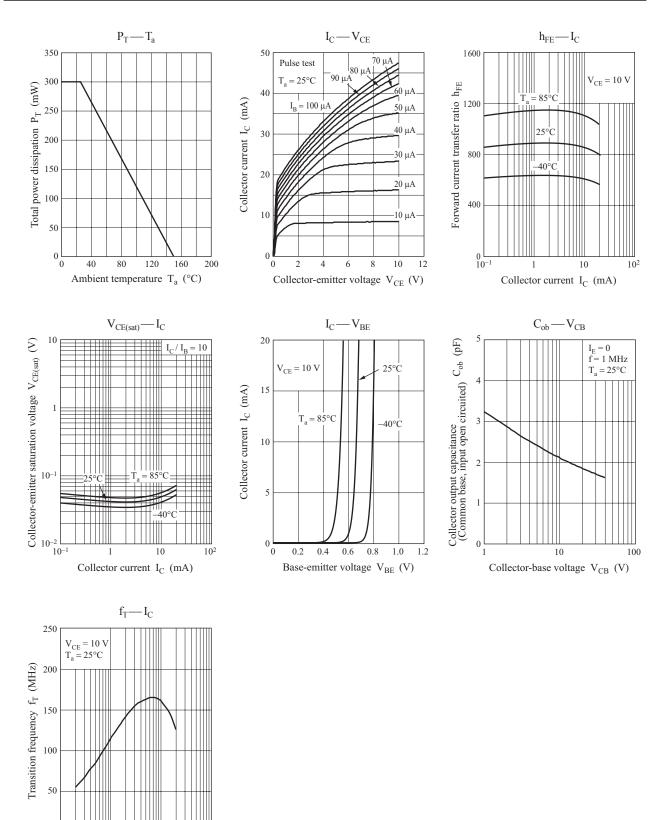


Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu {\rm A}, I_{\rm E} = 0$	100			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	100			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_{\rm E} = 10 \ \mu {\rm A}, I_{\rm C} = 0$	15			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 60 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 60 \text{ V}, I_{B} = 0$			1	μΑ
Forward current transfer ratio	\mathbf{h}_{FE}	$V_{CE} = 10 \text{ V}, I_C = 2 \text{ mA}$	400		1 200	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 1 \text{ mA}$		0.05	0.20	V
Transition frequency	\mathbf{f}_{T}	$V_{CE} = 10 \text{ V}, I_C = 2 \text{ mA}$		140		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Panasonic



Collector current I_C (mA)

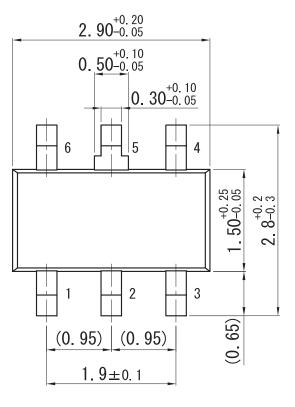
1

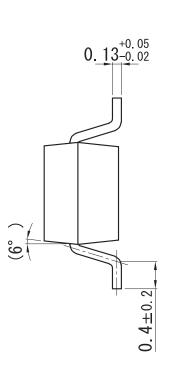
10

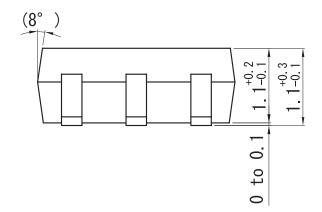
 10^{2}

0 L 10⁻¹

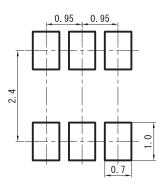
Mini6-G4-B







Land Pattern (Reference) (Unit: mm)



Unit: mm

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